

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15746098	
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PATENT		

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ATTORNEY DOCKET NUMBER:	LFD-0011-IN
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NAME OF SUBMITTER:	JAE Y. PARK
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SIGNATURE:	/Jae Y. Park/
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DATE SIGNED:	01/29/2018
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	This document serves as an Oath/Declaration (37 CFR 1.63).
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Total Attachments: 2

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UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Insert Name(s)
and Address(es)

WHEREAS, Sung Sik YUN of (Ujangsan Hillstate Apt., Naebalsan-dong) #113-602,
348, Gangseo-ro, Gangseo-gu, Seoul 07651, Republic of Korea

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

Insert Title
of Invention

WEARABLE SMART DEVICE HAVING FLEXIBLE SEMICONDUCTOR PACKAGE
MOUNTED ON A BAND

which claims priority to Korean Application No(s). 10-2015-0108806, filed on July 31, 2015,
and 10-2015-0108810, filed on July 31, 2015, and for which the undersigned is (are) about to
file an application for Letters Patent of the United States; and

Insert Name(s)
and Address(es)

WHEREAS, Young Hee SONG of (Parkview, Jeongja-dong) #603-205, 248, Jeongja-ro,
Bundang-gu, Seongnam-si, Gyeonggi-do 13554, Republic of Korea; Hyunk LEE of (Bellagio,
Dujeong-dong) #402-ho, Dujeongsangga 13-gil, Seobuk-gu, Cheonan-si, Chungcheongnam-do,
31106, Republic of Korea; Ki Hong SONG of (Sinbanpo Apt., Jamwon-dong) #216-206, 171,
Sinbanpo-ro, Seocho-gu, Seoul 06509, Republic of Korea; Jun Hee JEONG of (Hyundai Apt,
Pungdeokcheon-dong) #101-1405, 18, Suji-ro 342beon-gil, Suji-gu, Yongin-si, Gyeonggi-do
16838, Republic of Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.

NOW, THEREFORE, to all whom it may concern, be it known that, for good and valuable consideration paid to the undersigned, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

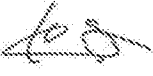
The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name of Inventor: Sung Sik YUN

Signature  Date 2018. 1. 24